

Electronic Patent Application Fee Transmittal

Application Number:	10529742
Filing Date:	06-Jan-2006
Title of Invention:	POLISHING PAD FOR SEMICONDUCTOR WAFER, POLISHING MULTILAYERED BODY FOR SEMICONDUCTOR WAFER HAVING SAME, AND METHOD FOR POLISHING SEMICONDUCTOR WAFER
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Attorney Docket Number:	268844USOPCT

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	3	3	9
Total in USD (\$)				1749